Sir:

Transmitted herewith for filing is the Patent Application of:

Inventor: CHII-MING WU, MING-HSING TSAI, CHING-HUA HSIEH, SHAU-LIN SHUE

For: METHOD OF MANUFACTURING A CONTACT INTERCONNECTION LAYER CONTAINING A METAL AND

NITROGEN BY ATOMIC LAYER DEPOSITION FOR DEEP SUB-MICRON SEMICONDUCTOR TECHNOLOGY

Enclosed are:					
X 6 sheets of drawing(s) - formal.					
X An assignment of the invention to Taiwan Semicondutor Manufacturing Co.					
An associate power of attorney Applicant claims small entity status					
Request & Certification under 35 USC 122(b)(2)(b)(i)					
The filing fee has been calculated as shown below:					
	(Col. 1) (Col. 2)		OTHER THAN A SMALL ENTITY		
FOR:	NO. FILED	NO, EXTRA	RATE	FEE	
BASIC FEE		><		\$ 750.	
TOTAL CLAIMS	51 -20=	31	x 18 =	\$ 558.	
INDEP CLAIMS	5 -3=	2	x 84 =	\$ 168.	
			SUB TOTAL	\$ 1,476.	
			ASSIGNMENT	\$40.	ı
			TOTAL	\$ 1,516.	
Please charge my Deposit Account No. 19-0033 in the amount of \$ 1,516. A duplicate copy of this sheet is enclosed.					
The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any					
overpayment to Deposit Account No. 19-0033. A duplicate copy of this sheet is enclosed.					
X Any additional filing fees required under 37 CFR §1.16.					
X Any patent application processing fees under 37 CFR §1.17.					
Respectfully submitted HOLD COLOR GEORGE O. SAILE, REG. NO. 19,572					

EXPRESS MAIL CERTIFICATE

Express Mail No.EV313927030US

I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to Assistant Commissioner of Patents, Alexandria, VA, 22313-1450. Applicant and/or Attorney requests the date of deposit as the Filing Date.

Date of deposit

Signature / Date